

Selection Guide

Part No.	Dice	Lens Type	Po(mW/sr) [2] @ 20mA		Viewing Angle [1]
			Min.	Typ.	2θ1/2
APTD3216SF4C	SF4 (GaAlAs)	WATER CLEAR	1.6	3.2	50°

Notes:

1. $\theta_{1/2}$ is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.
2. Radiant Intensity/ luminous flux: +/-15%.

Electrical / Optical Characteristics at T_A=25°C

Parameter	P/N	Symbol	Typ.	Max.	Units	Test Conditions
Forward Voltage [1]	SF4	V _F	1.3	1.6	V	I _F =20mA
Reverse Current	SF4	I _R	-	10	uA	V _R =5V
Capacitance	SF4	C	90	-	pF	V _F =0V;f=1MHz
Peak Spectral Wavelength	SF4	λ _P	880	-	nm	I _F =20mA
Spectral Bandwidth	SF4	Δλ _{1/2}	50	-	nm	I _F =20mA

Note:

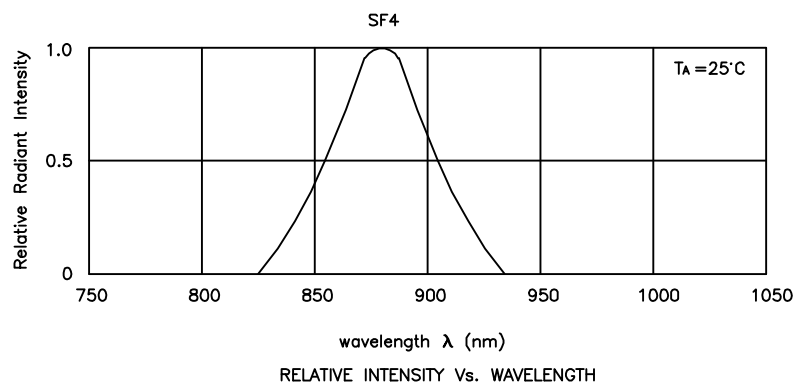
1. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at T_A=25°C

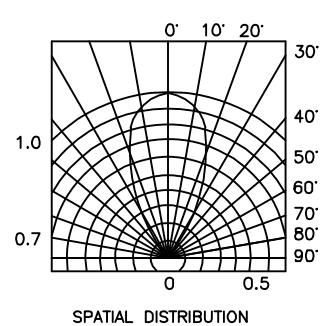
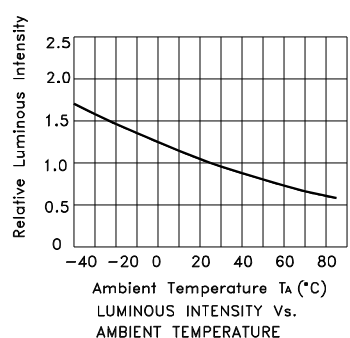
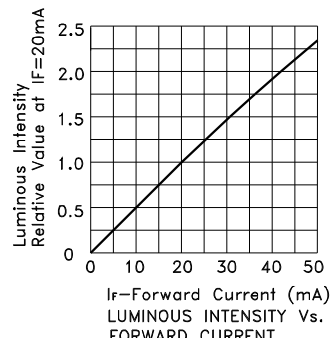
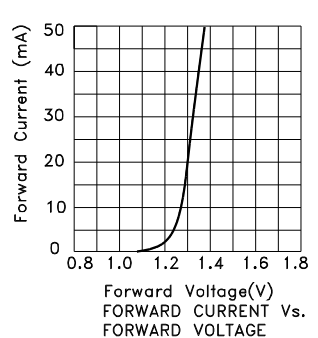
Parameter	Symbol	SF4	Units
Power Dissipation	P _T	80	mW
DC Forward Current	I _F	50	mA
Peak Forward Current [1]	i _{FS}	1.2	A
Reverse Voltage	V _R	5	V
Operating Temperature	T _A	-40 To +85	°C
Storage Temperature	T _{STG}	-40 To +85	°C

Note:

1. 1/100 Duty Cycle, 10μs Pulse Width.

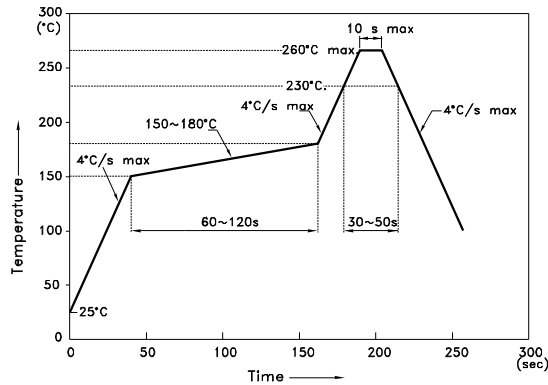


APTD3216SF4C



APTD3216SF4C

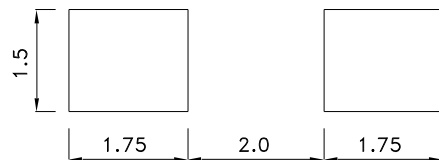
Reflow Soldering Profile For Lead-free SMT Process.



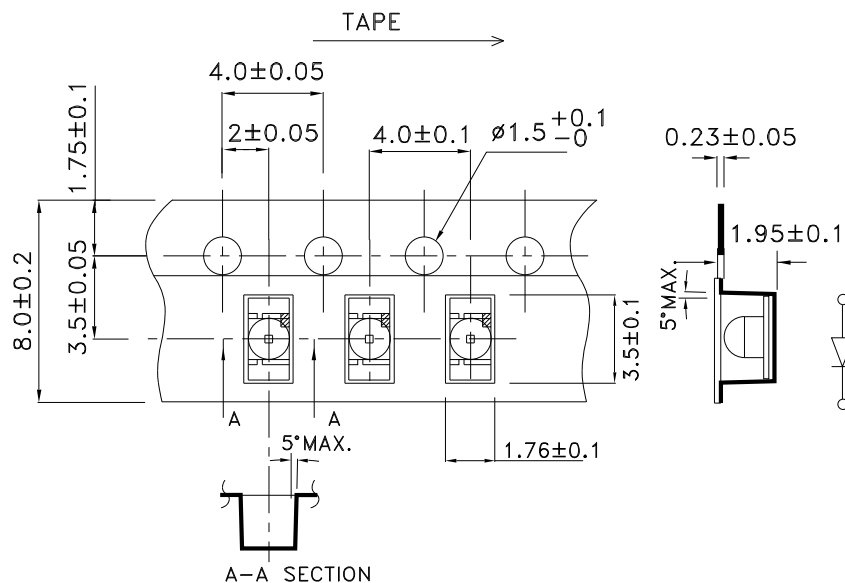
NOTES:

1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)

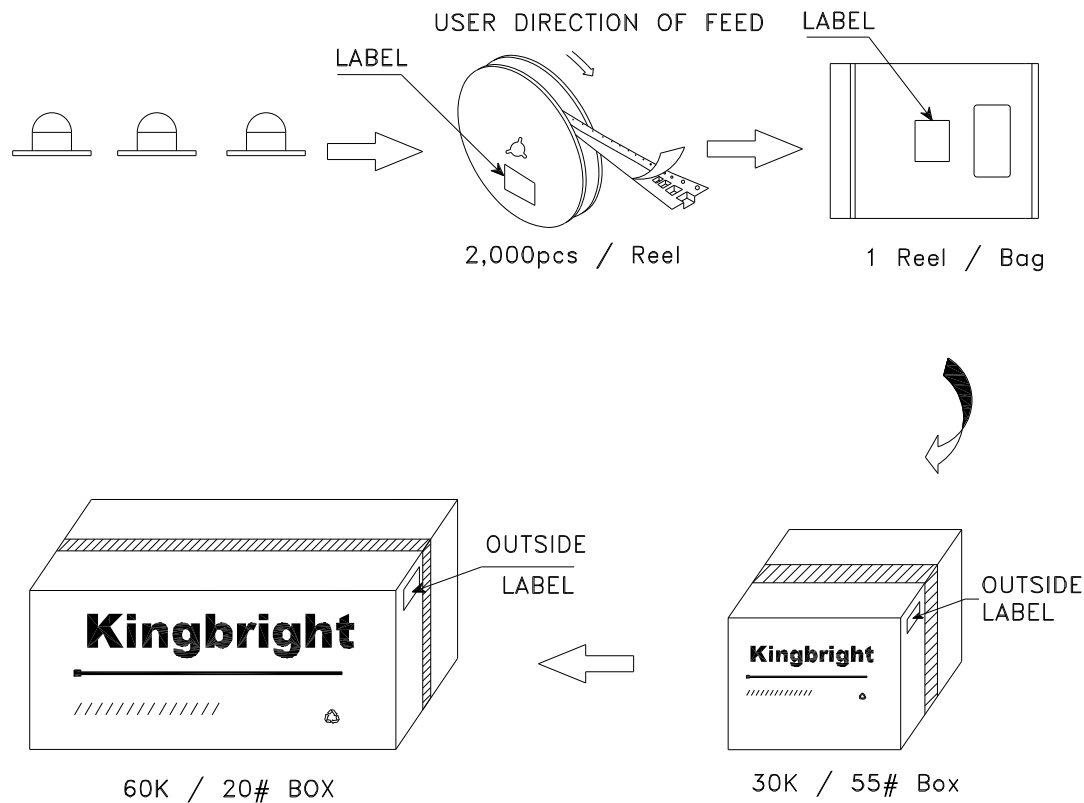


Tape Specifications (Units : mm)



PACKING & LABEL SPECIFICATIONS

APTD3216SF4C



Kingbright	
P/NO: APTD3216xxx	
QTY: 2,000 pcs	Q.C. Q C xx xx xxxx PASSED
S/N: XXXX	
CODE: XXX	
LOT NO:	
 xxxxxxxxxxxxxxxxxxxxxxxxxxxx	
RoHS Compliant	